

What is claimed is:

1. A device comprising:
a sub-mount containing conductive traces;
an edge-emitting laser electrically coupled to the conductive traces; and
a reflector positioned to reflect an optical signal from the edge-emitting laser through the sub-mount.
2. The device of claim 1, further comprising an alignment post attached to the sub-mount where the optical signal emerges from the sub-mount.
3. The device of claim 1, further comprising a lens in the path of the optical signal.
4. The device of claim 3, wherein the lens is integrated in the sub-mount along the path of the optical signal.
5. The device of claim 3, wherein the lens comprises a diffractive optical element.
6. The device of claim 1, wherein the reflector comprises a portion of an inner wall of a cavity in a cap overlying the die.
7. The device of claim 6, wherein the cap attaches to the sub-mount to hermetically seal the die in the cavity.
8. The device of claim 1, further comprising a transparent encapsulant attached to the sub-mount and encasing the die.
9. The device of claim 8, wherein the encapsulant comprises silicone.
10. A process comprising:
electrically connecting a laser to a sub-mount; and
attaching a reflector to the sub-mount in a position such that an optical signal from the laser is reflected through the sub-mount.

11. The process of claim 10, further comprising attaching an alignment post to the sub-mount where the optical signal emerges.

12. The process of claim 10, further comprising encapsulating the laser in a transparent material that protects the laser.

13. The process of claim 12, wherein the transparent material comprises silicone.

14. The process of claim 10, wherein the laser is an edge-emitting laser.

15. The process of claim 10, wherein electrically connecting the laser comprises connecting a plurality of lasers to a sub-mount wafer that includes the sub-mount.

16. The process of claim 15, further comprising cutting the sub-mount wafer to separate the sub-mount from similar sub-mounts.